

0.9-1.8GHz Medium Power Amplifier

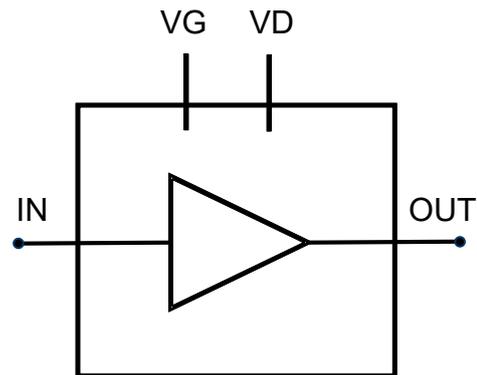
GaAs Monolithic Microwave IC

Description

The CHA5005-99F is a monolithic one-stage driver amplifier that produces 26.5dBm output power associated to 33% power added efficiency at 1dB gain compression. It is designed for a wide range of applications, from military to commercial communication systems.

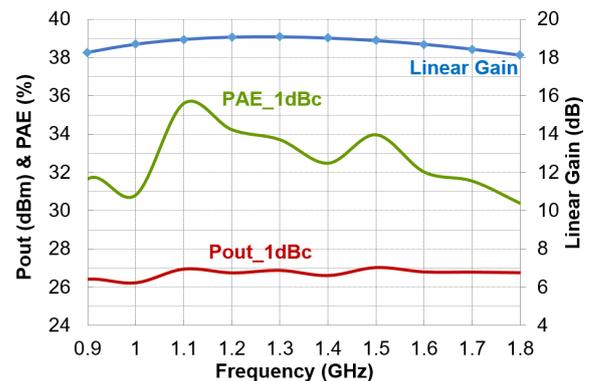
The circuit is manufactured with a pHEMT process, 0.25µm gate length, via holes through the substrate, air bridges and electron beam gate lithography.

It is supplied as bare die.



Main Features

- Broadband performances: 0.9-1.8GHz
- 26.5dBm Pout @ 1dB gain compression
- 33% PAE @ 1dB gain compression
- 18.5dB Linear Gain
- DC bias: Vd=7.5Volt@Id=120mA



Main Electrical Characteristics

Tb = +25°C

Symbol	Parameter	Min	Typ	Max	Unit
Freq	Frequency range	0.9		1.8	GHz
Gain	Linear Gain		18.5		dB
P _{-1dB}	Output Power @1dB comp.		26.5		dBm
PAE _{P-1dB}	Power Added Efficiency @1dB comp.		33		%

Specifications

Tb = +25°C, Vd = +7.5V, Id = 120mA. CW mode.

Symbol	Parameter	Min	Typ	Max	Unit
Freq	Frequency range	0.9		1.8	GHz
Gain	Linear Gain		18.5		dB
RL_in	Input Return Loss		12		dB
RL_out	Output Return Loss		12		dB
P _{-1dB}	Output Power @1dB comp.		26.5		dBm
PAE _{P-1dB}	Power Added Efficiency @1dB comp.		33		%
Id _{P-1dB}	Supply drain current @1dB comp.		190		mA
P _{-3dB}	Output Power @3dB comp.		28		dBm
PAE _{P-3dB}	Power Added Efficiency @3dB comp.		38		%
Id _{P-3dB}	Supply drain current @3dB comp.		220		mA
Vd	Drain bias voltage		7.5		V
Id	Quiescent bias drain current		120		mA
Vg	Gate bias voltage		-0.45		V

These values are representative of onboard measurements as defined on the drawing in paragraph "Evaluation mother board".

Absolute Maximum Ratings ⁽¹⁾

Tb = +25°C

Symbol	Parameter	Values	Unit
Vd	Drain bias voltage	9.5	V
Id _{max}	Drain current @ maximum input power	270	mA
Pin	Maximum input power	17	dBm
Vg	Gate bias voltage	-3 to -0.3	V

⁽¹⁾ Operation of this device above anyone of these parameters may cause permanent damage.

Recommended Operating Range ^{(2), (3)}

Symbol	Parameter	Values	Unit
Vd	Drain bias voltage	8	V
Idq	Drain bias quiescent current	200	mA
Pin	Maximum input power	15	dBm
Vg	Gate bias voltage	-2.5 to -0.35	V
Tj	Maximum Junction temperature ⁽⁴⁾	175	°C

⁽²⁾ Electrical performances are defined for specified test conditions.

⁽³⁾ Electrical performances are not guaranteed over all recommended operating conditions.

⁽⁴⁾ See "Device thermal performances" paragraph.

Temperature Range

Tcase	Operating temperature range	-40 to +85	°C
Tstg	Storage temperature range	-55 to +150	°C

Typical Bias Conditions

Tb = +25°C

Symbol	Pad N°	Parameter	Values	Unit
Vd	22	Drain bias voltage	7.5	V
Vg	24	Gate bias voltage	-0.45	V

“Power ON” sequence

1. Bias MPA gate voltage at Vg close to Vpinch-off (Typically: Vg ≈ -1.5V)
2. Apply Vd bias voltage (Typically: Vd = 7.5V)
3. Increase Vg up to quiescent bias drain current Id
4. Apply RF signal

“Power OFF” sequence

1. Turn off RF signal
2. Bias MPA gate voltage at Vg close to Vpinch-off (Typically: Vg ≈ -1.5V)
3. Turn Vd bias voltage to 0V
4. Turn Vg bias voltage to 0V

Device thermal performance

All the figures given in this section are obtained assuming that the bare die is only cooled down by conduction (no convection mode considered).

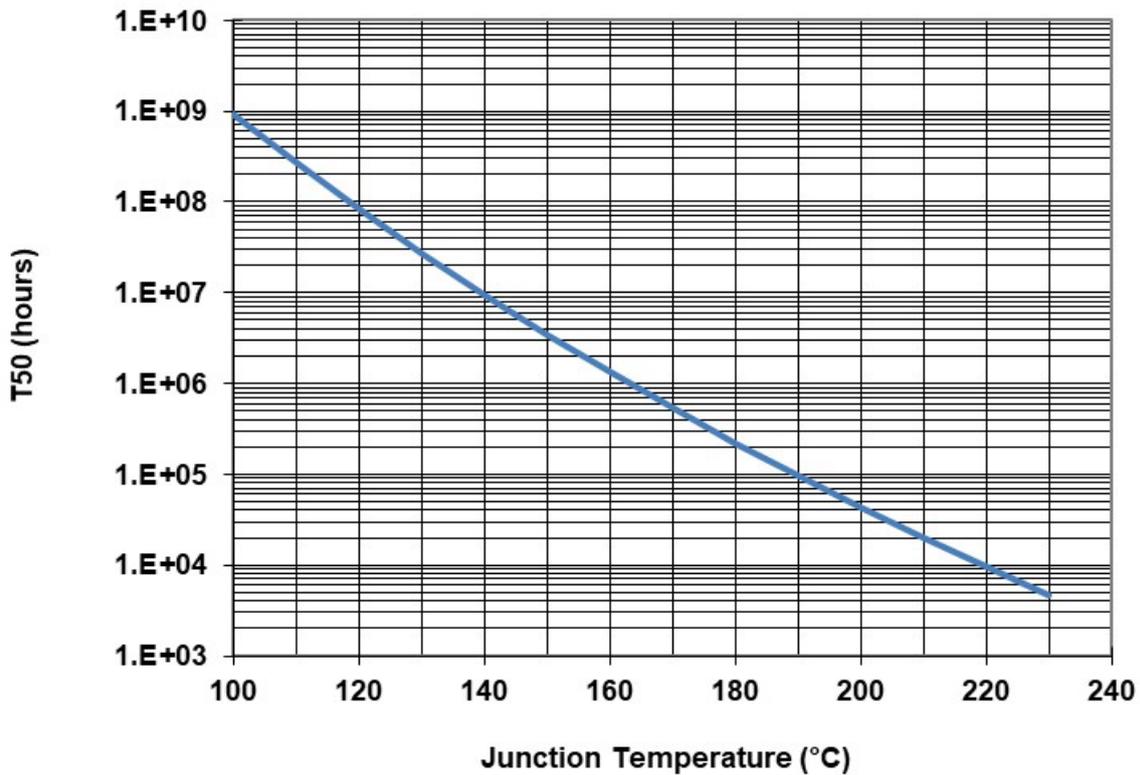
The temperature is monitored at the die back-side interface (T_b).

The system maximum temperature must be adjusted in order to guarantee that $T_{junction}$ remains below the maximum value specified in the Absolute Maximum Ratings table.

So, the system PCB must be designed to comply with this requirement.

Parameter	Biasing conditions	$T_{junction}$ (°C)	R_{TH} (°C/W)	T_{50} (hours)
$R_{TH}^{(1)}$ Thermal Resistance (Junction to Chip back side)	$V_d = 7.5V$ $I_d = 120mA$, $I_{d_drive} = 210mA$ $P_{diss} = 1W$ in CW Mode	155	65.4	$2E+06$

⁽¹⁾ Assuming $T_b = 85^\circ C$



Typical bare die (without wire bondings) Sij parameters

Tb = +25°C, Vd = +7.5V, Idq = 120mA (from on wafer measurements)

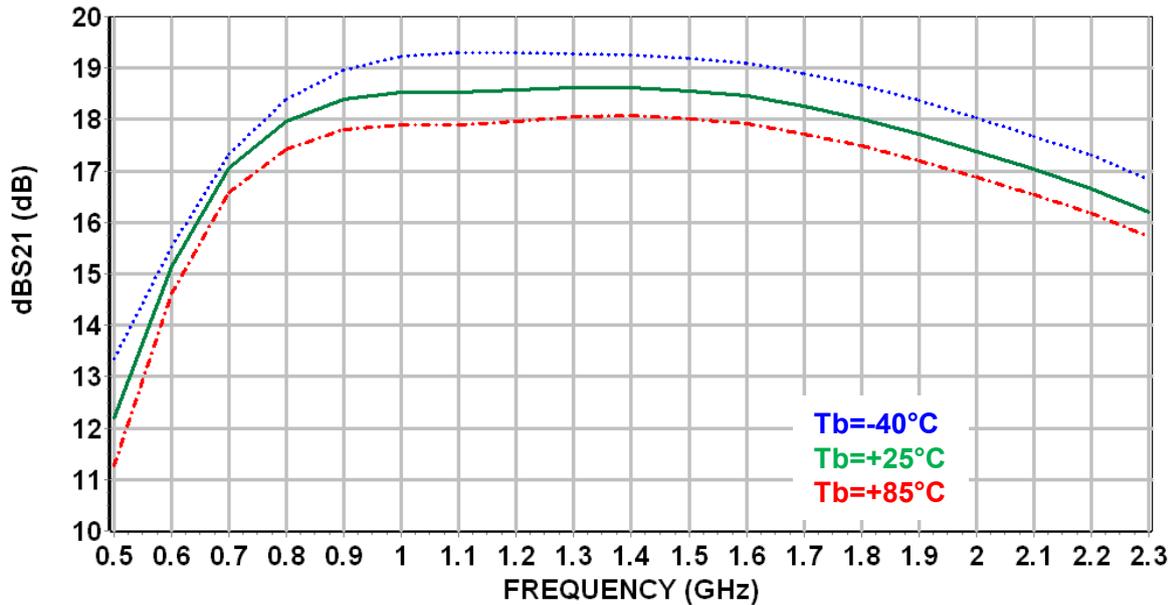
Freq (GHz)	S11 (dB)	PhS11 (°)	S12 (dB)	PhS12 (°)	S21 (dB)	PhS21 (°)	S22 (dB)	PhS22 (°)
0.3	-1.83	-54.88	-31.18	-129.21	-2.26	-79.27	-2.26	-74.20
0.4	-3.21	-76.28	-31.44	167.15	3.70	-54.45	-3.63	-104.39
0.5	-4.96	-97.35	-30.14	110.35	9.61	-67.31	-4.96	-128.92
0.6	-10.63	-124.26	-31.56	92.86	14.97	-90.89	-7.93	-156.42
0.7	-15.40	-106.60	-28.68	68.68	16.93	-122.54	-10.25	-169.37
0.8	-16.85	-91.97	-27.68	45.86	17.84	-146.11	-12.20	172.12
0.9	-17.03	-81.00	-27.25	27.12	18.39	-165.90	-14.71	149.28
1	-16.52	-76.09	-27.01	10.59	18.70	176.96	-17.26	120.38
1.1	-15.78	-76.01	-26.85	-4.36	18.86	161.51	-19.04	82.85
1.2	-14.97	-80.06	-26.87	-17.92	18.96	147.32	-18.42	43.67
1.3	-14.19	-86.90	-26.91	-30.11	18.96	134.18	-16.53	14.81
1.4	-13.45	-95.78	-27.02	-41.60	18.91	121.63	-14.46	-6.12
1.5	-12.77	-106.30	-27.19	-52.97	18.81	109.53	-12.67	-21.73
1.6	-12.08	-117.73	-27.39	-63.37	18.66	98.02	-11.14	-34.48
1.7	-11.37	-129.76	-27.66	-73.06	18.47	86.89	-9.86	-45.32
1.8	-10.67	-141.95	-28.01	-82.68	18.24	76.05	-8.79	-55.34
1.9	-9.96	-154.28	-28.34	-92.08	17.97	65.59	-7.88	-64.52
2	-9.29	-165.96	-28.74	-101.30	17.65	55.52	-7.09	-72.91
2.1	-8.60	-177.17	-29.30	-109.70	17.30	45.72	-6.44	-80.94
2.2	-7.92	172.38	-29.79	-117.73	16.95	36.00	-5.92	-88.63
2.3	-7.31	162.28	-30.25	-125.75	16.53	26.65	-5.46	-95.72
2.4	-6.73	152.91	-30.71	-132.41	16.11	17.87	-5.05	-102.27
2.5	-6.21	144.19	-31.25	-140.16	15.68	9.26	-4.73	-108.70
2.6	-5.73	136.09	-31.82	-146.56	15.24	0.87	-4.48	-114.76
2.7	-5.29	128.59	-32.27	-153.16	14.78	-7.28	-4.26	-120.64
2.8	-4.90	121.48	-32.66	-158.74	14.35	-15.22	-4.10	-126.35
2.9	-4.55	114.84	-33.52	-164.34	13.88	-22.95	-3.97	-131.59
3	-4.22	108.65	-33.97	-171.40	13.45	-30.66	-3.88	-136.64
3.1	-3.93	102.96	-34.50	-174.07	13.00	-37.92	-3.83	-141.38
3.2	-3.67	97.53	-35.03	-179.03	12.57	-45.28	-3.79	-145.90
3.3	-3.44	92.30	-35.55	-173.74	12.15	-52.53	-3.78	-150.20
3.4	-3.23	87.58	-36.01	-170.57	11.72	-59.76	-3.78	-154.30
3.5	-3.04	83.12	-36.46	-164.87	11.30	-66.89	-3.79	-158.15
3.6	-2.88	78.75	-37.03	-159.92	10.89	-74.10	-3.83	-161.71
3.7	-2.71	74.72	-37.26	-154.68	10.47	-81.24	-3.87	-165.10
3.8	-2.58	70.86	-37.69	-149.99	10.05	-88.45	-3.90	-168.20
3.9	-2.46	67.22	-38.38	-145.91	9.63	-95.69	-3.93	-171.11
4	-2.35	63.67	-38.58	-142.68	9.18	-103.15	-3.94	-173.89

Typical Board Measurements: S-parameters measurements

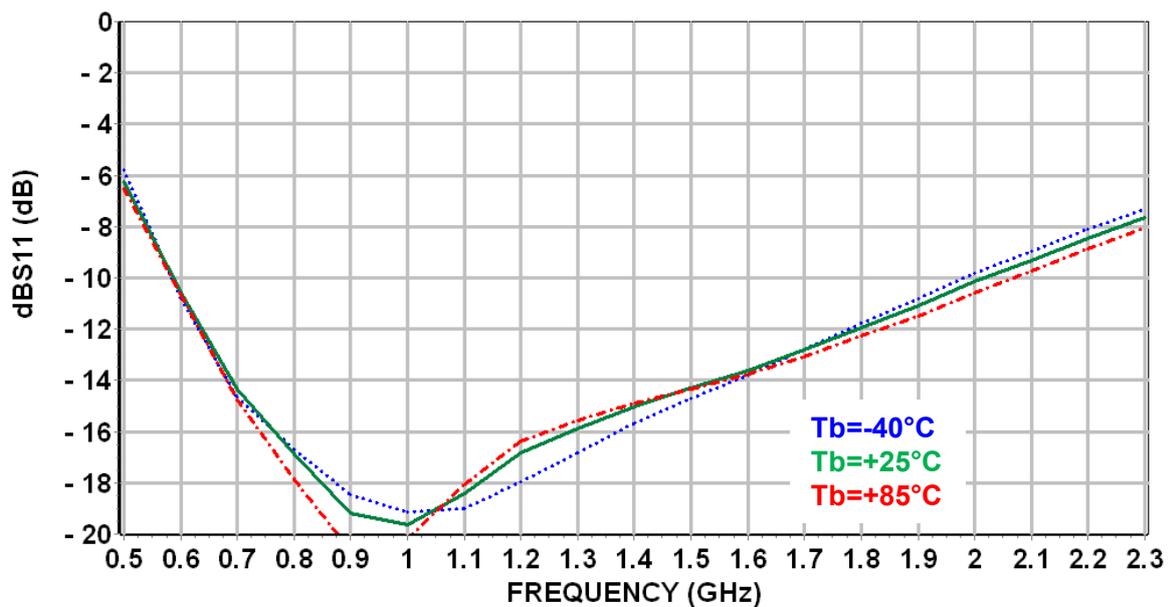
Biassing conditions: $V_d = +7.5V$, $I_{dq} = 120mA$ set at $T_b = +25^\circ C$, kept constant vs temperature.
 Temperature conditions $T_{backside} = -40^\circ C, +25^\circ C, +85^\circ C$

Measurements are given in the connectors' access plans, using the board given in the paragraph "Evaluation board".
 CW measurements

Linear Gain versus Frequency & Temperature



Input Return Loss versus Frequency & Temperature

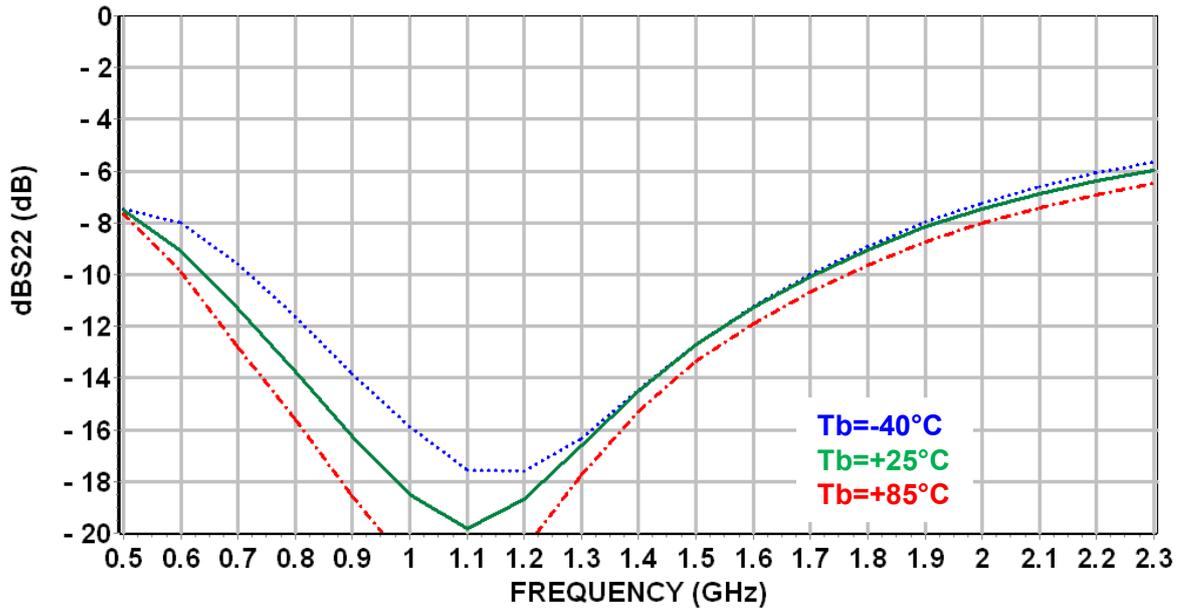


Typical Board Measurements: S-parameters measurements

Biassing conditions: $V_d = +7.5V$, $I_{dq} = 120mA$ set at $T_b = +25^\circ C$, kept constant vs temperature.
Temperature conditions $T_{backside} = -40^\circ C, +25^\circ C, +85^\circ C$

Measurements with temperature are given in the connectors' access plans, using the board given in the paragraph "Evaluation board".

Output Return Loss versus Frequency & Temperature



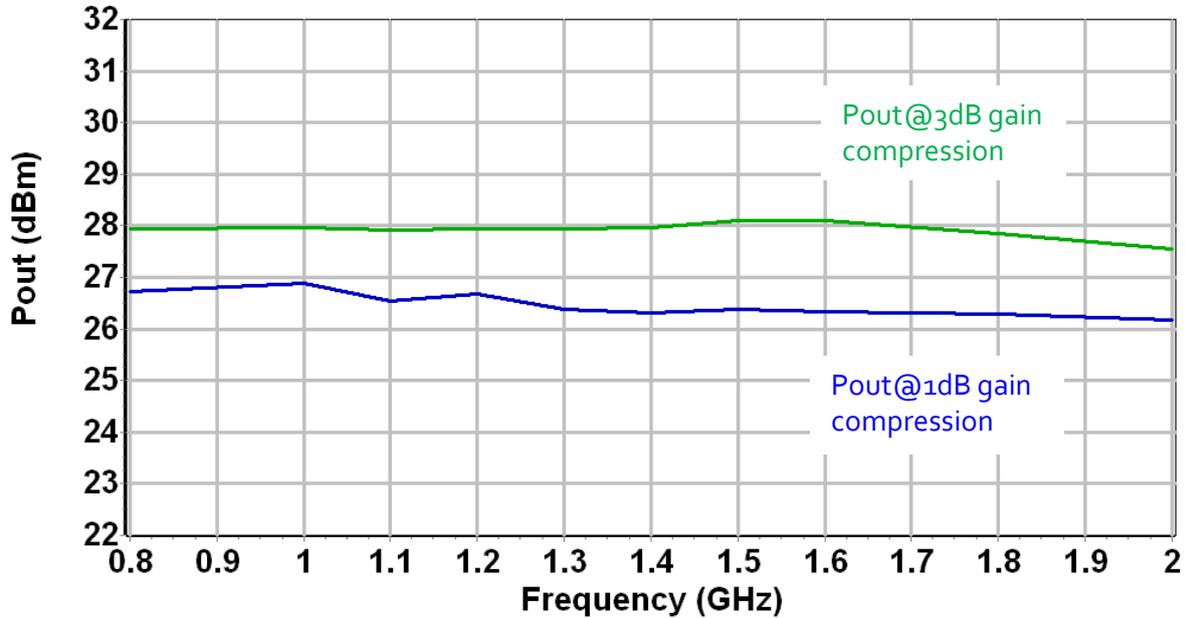
Typical Board Measurements: Power measurements

Tb = +25°C, Vd = +7.5V, Idq = 120mA

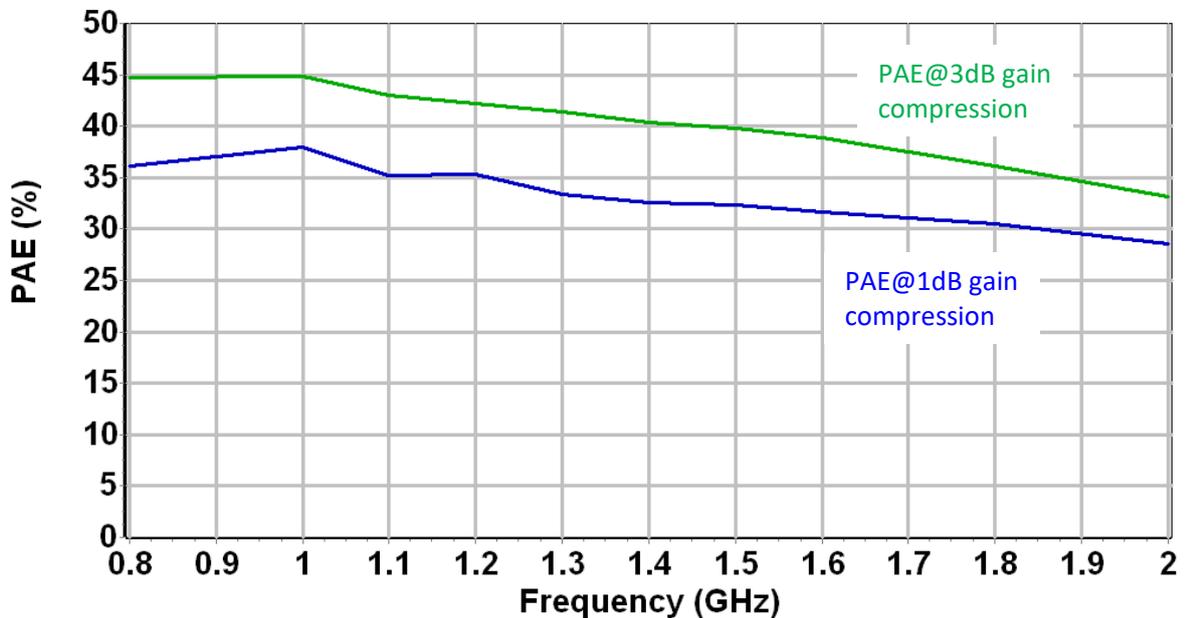
Measurements are given in the connectors' access plans, using the board given in the paragraph "Evaluation board".

CW measurements

Output Power @ 1dB & 3dB gain compression versus Frequency



Power Added Efficiency @ 1dB & 3dB gain compression versus Frequency



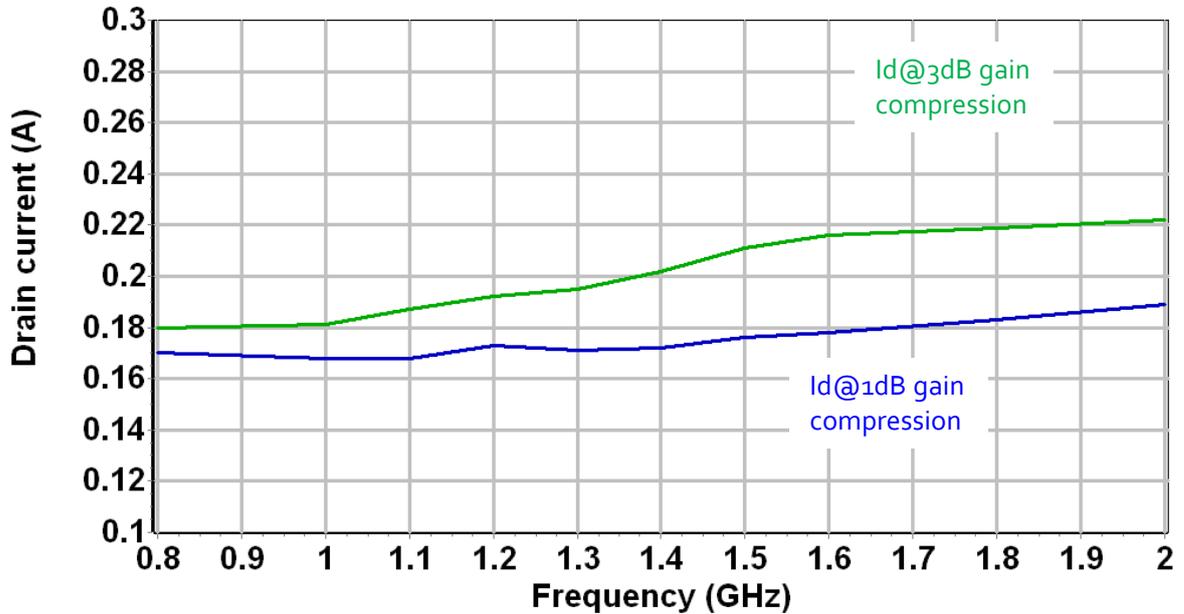
Typical Board Measurements: Power measurements

T_b = +25°C, V_d = +7.5V, I_{dq} = 120mA

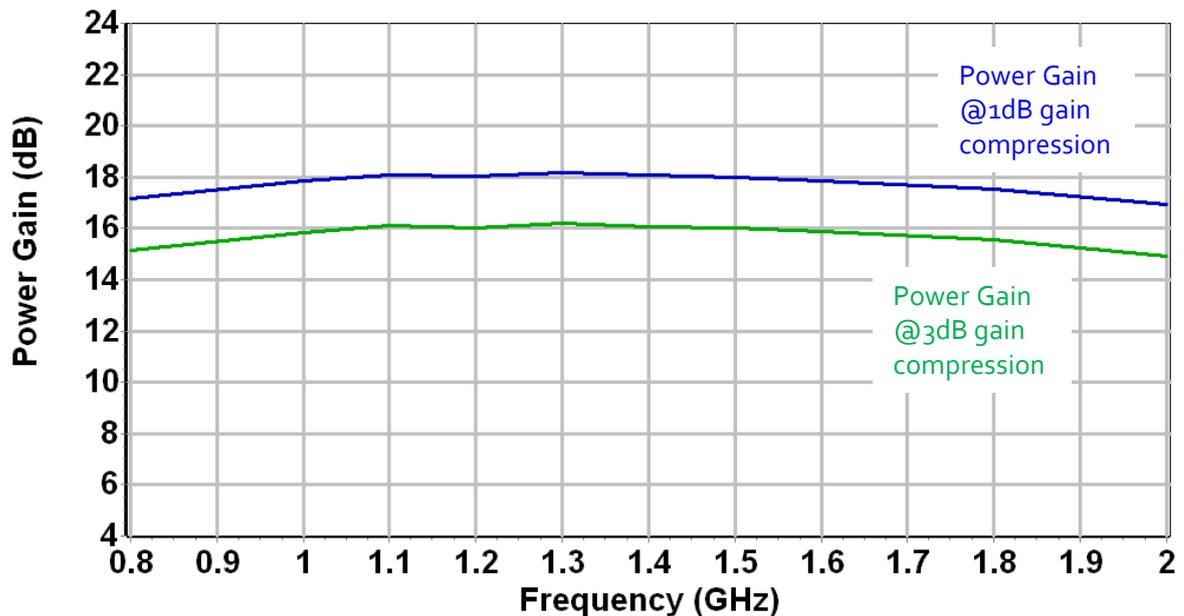
Measurements are given in the connectors' access plans, using the board given in the paragraph "Evaluation board".

CW measurements

Drain Current @ 1dB & 3dB gain compression versus Frequency



Power Gain @ 1dB & 3dB gain compression versus Frequency



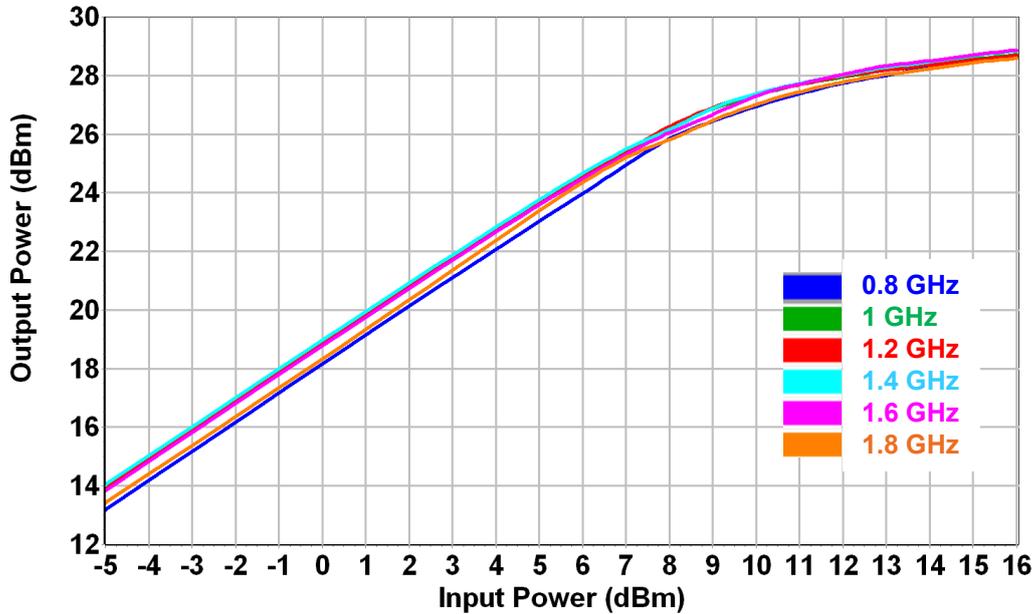
Typical Board Measurements: Power measurements

Tb = +25°C, Vd = +7.5V, Idq = 120mA

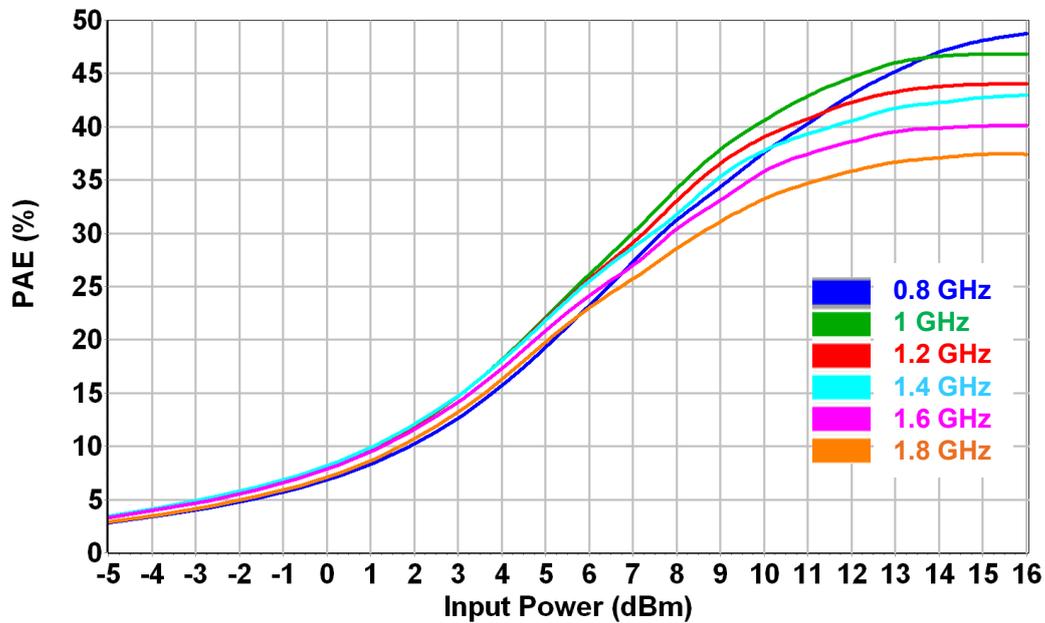
Measurements are given in the connectors' access plans, using the board given in the paragraph "Evaluation board".

CW measurements

Output Power versus Input Power and versus Frequency



Power Added Efficiency versus Input Power and versus Frequency



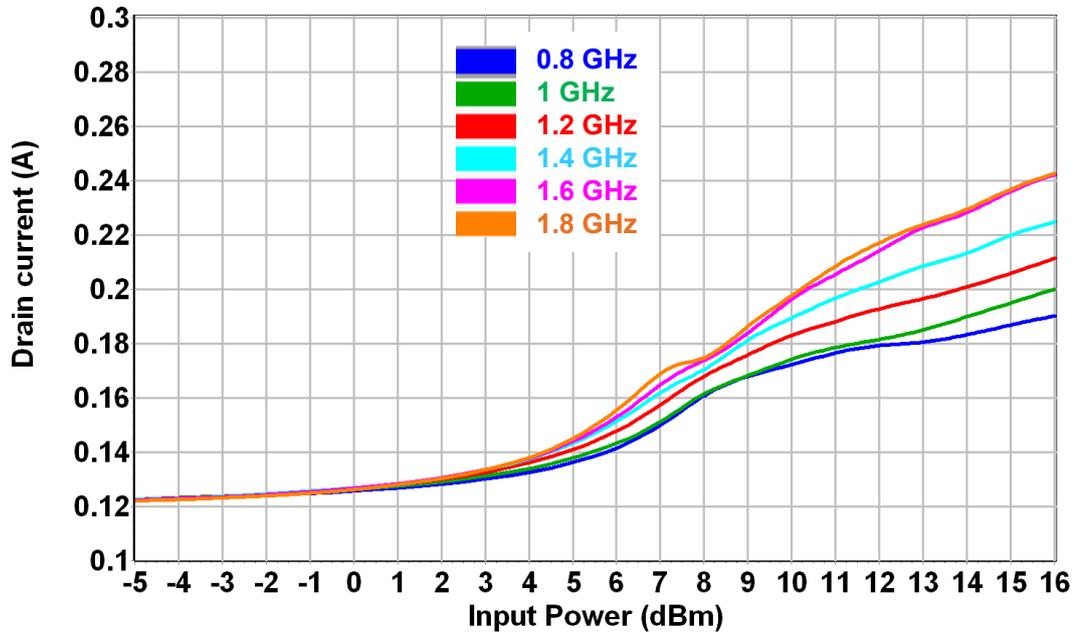
Typical Board Measurements: Power measurements

Tb = +25°C, Vd = +7.5V, Idq = 120mA

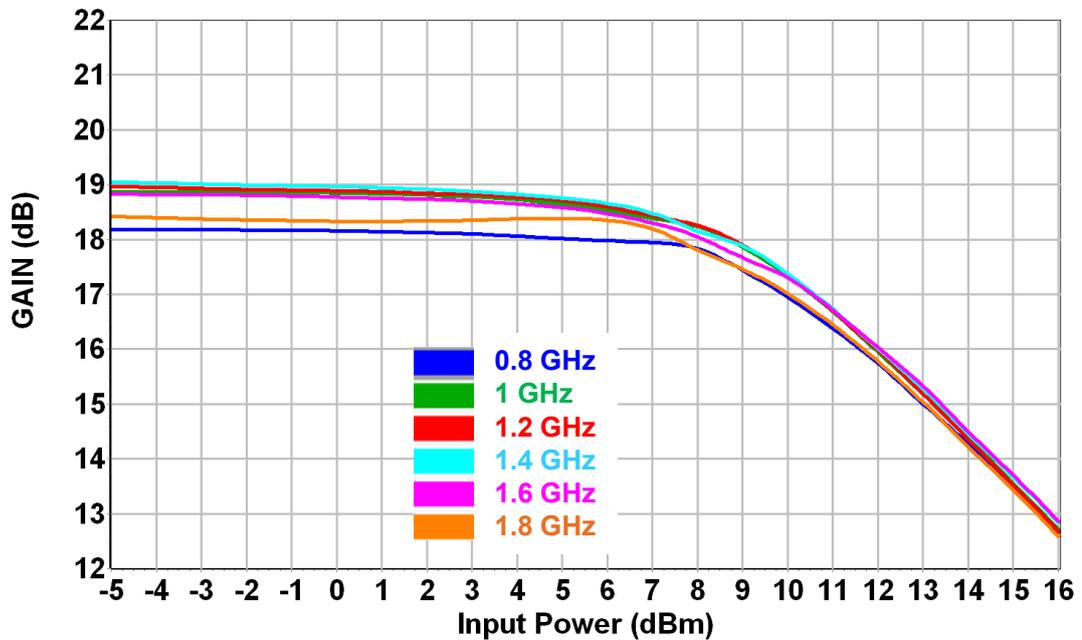
Measurements are given in the connectors' access plans, using the board given in the paragraph "Evaluation board".

CW measurements

Drain Current versus Input Power and versus Frequency



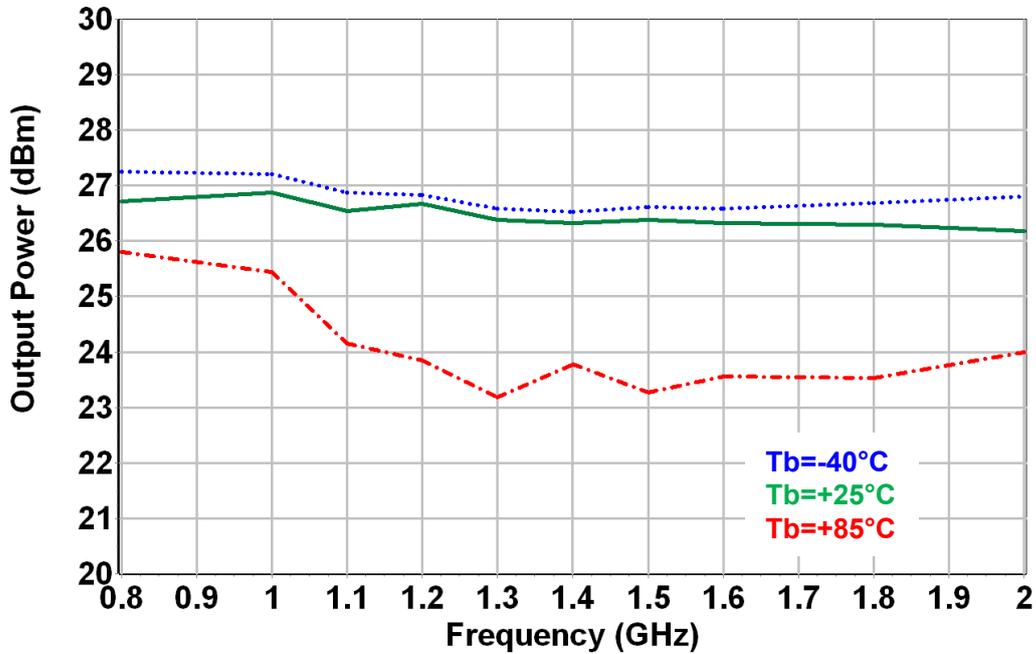
Power Gain versus Input Power and versus Frequency



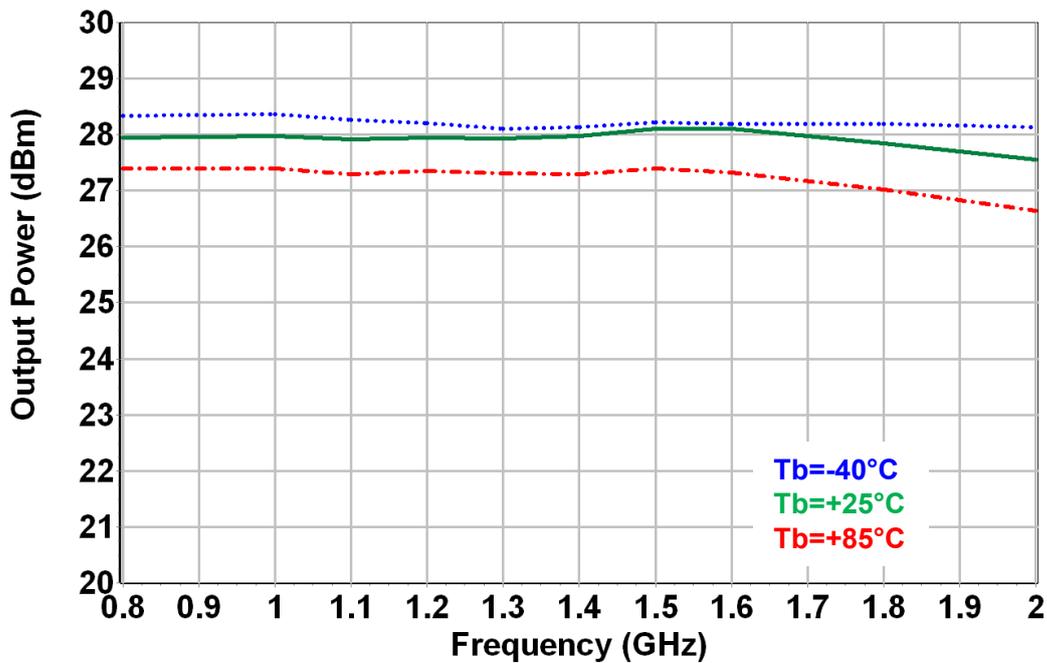
Typical Board Measurements: Power measurements

Biasing conditions: $V_d = +7.5V$, $I_{dq} = 120mA$ set at $T_b = +25^\circ C$, kept constant vs temperature.
 Temperature conditions $T_{backside} = -40^\circ C, +25^\circ C, +85^\circ C$
 CW measurements

Output Power @ 1dB Gain compression



Output Power @ 3dB Gain compression



Typical Board Measurements: Power measurements

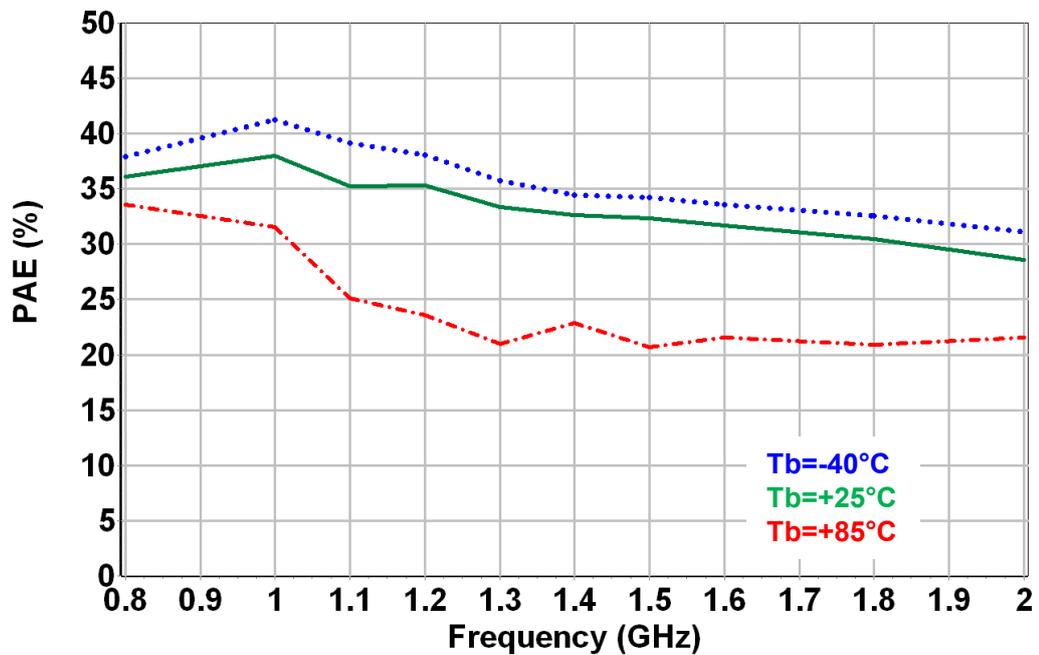
Biasing conditions: $V_d = +7.5V$, $I_{dq} = 120mA$ set at $T_b = +25^\circ C$, kept constant vs temperature.

Test conditions at $T_{backside} = -40^\circ C / +25^\circ C / +85^\circ C$

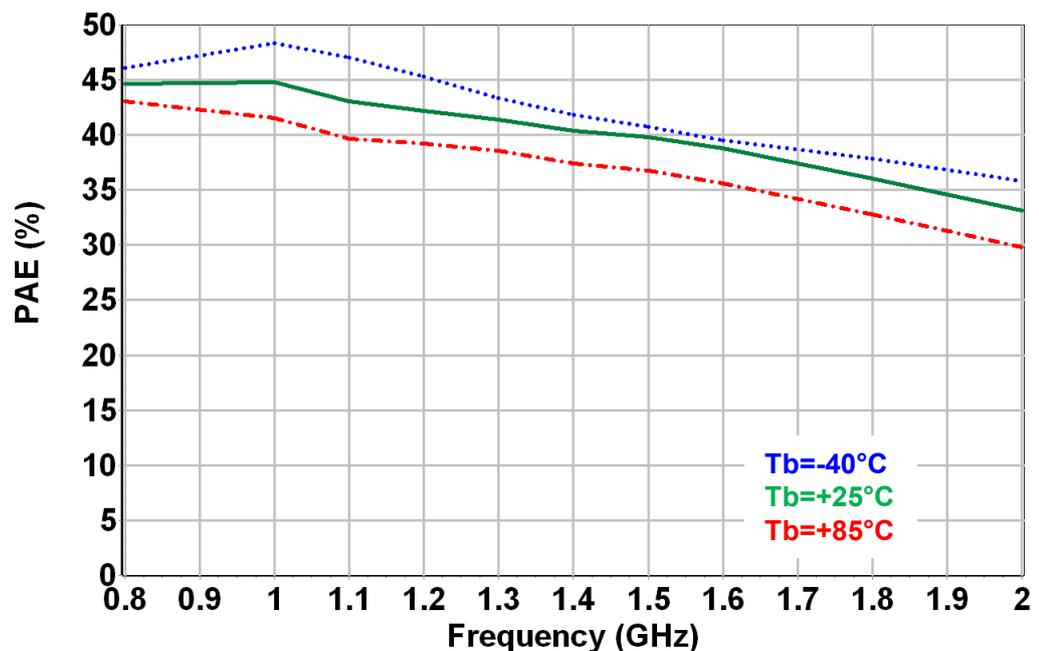
Measurements are given in the connectors' access plans, using the board given in the paragraph "Evaluation board".

CW measurements

PAE @ 1dB Gain compression



PAE @ 3dB Gain compression



Typical Board Measurements: Power measurements

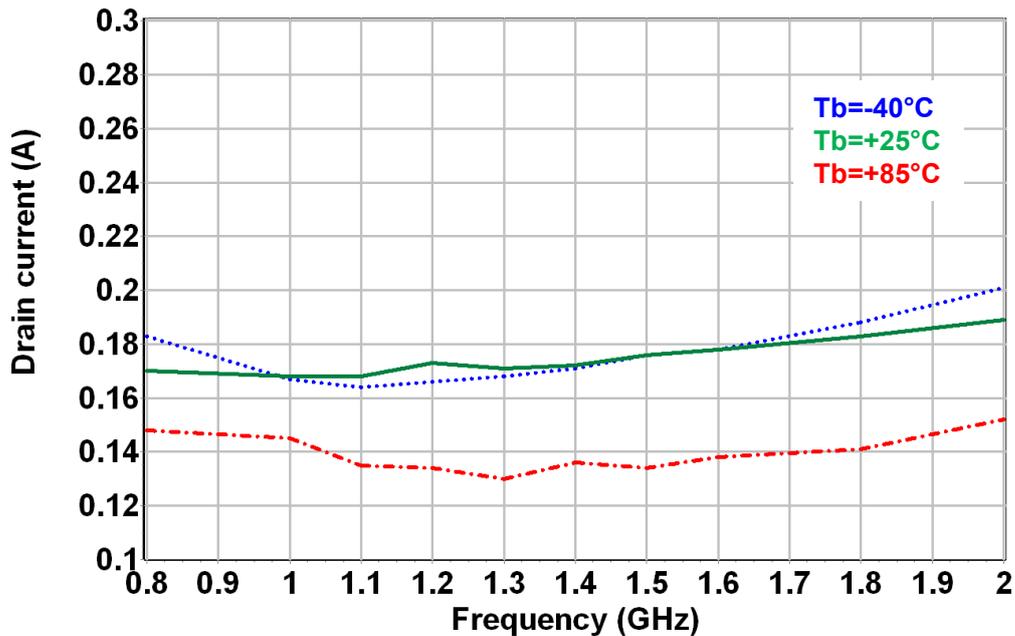
Biasing conditions: $V_d = +7.5V$, $I_{dq} = 120mA$ set at $T_b = +25^\circ C$, kept constant vs temperature.

Test conditions at $T_{backside} = -40^\circ C / +25^\circ C / +85^\circ C$

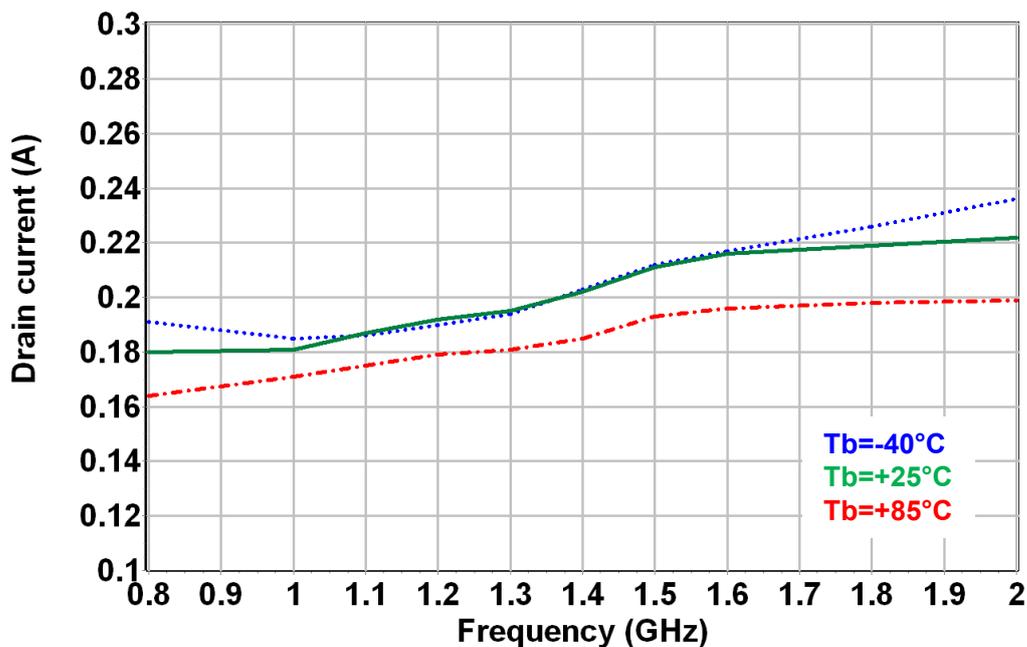
Measurements are given in the connectors' access plans, using the board given in the paragraph "Evaluation board".

CW measurements

Drain current @ 1dB Gain compression vs Freq and Temp



Drain current @ 3dB Gain compression vs Freq and Temp



Typical Board Measurements: Power measurements

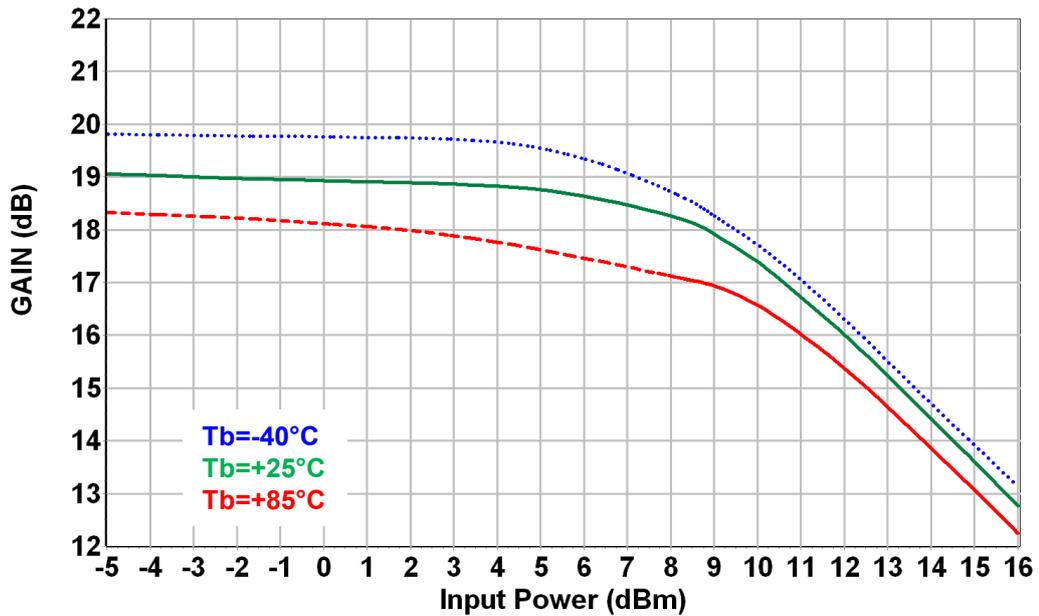
Biasing conditions: $V_d = +7.5V$, $I_{dq} = 120mA$ set at $T_b = +25^\circ C$, kept constant vs temperature.

Test conditions at $T_{backside} = -40^\circ C / +25^\circ C / +85^\circ C$

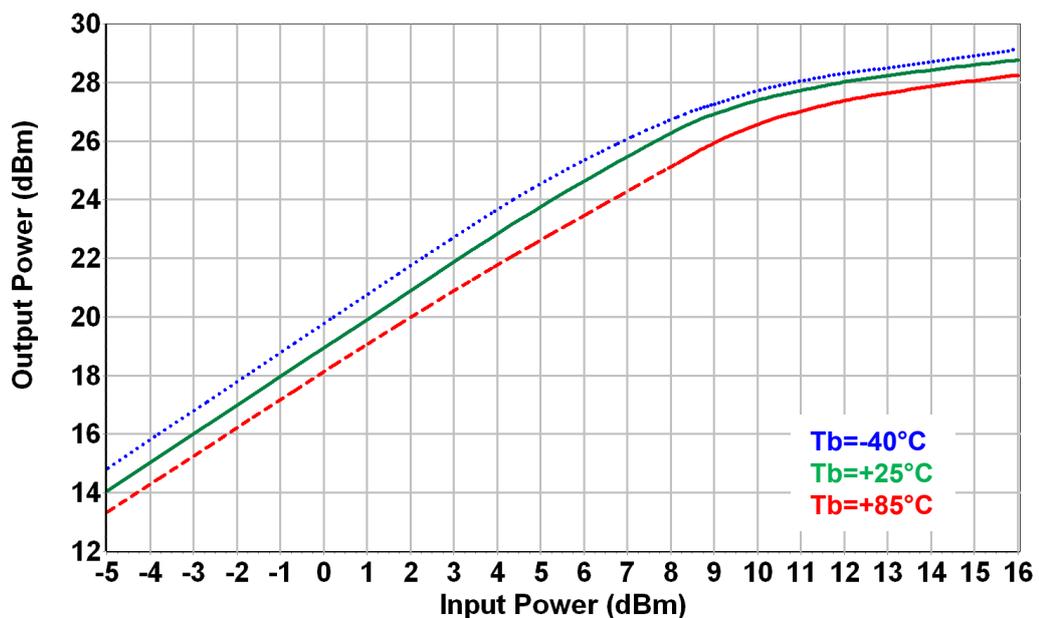
Frequency : 1.3 GHz in CW measurements

Measurements are given in the connectors' access plans, using the board given in the paragraph "Evaluation board".

Power Gain versus input power and Temp



Output Power versus input power and Temp



Typical Board Measurements: Power measurements

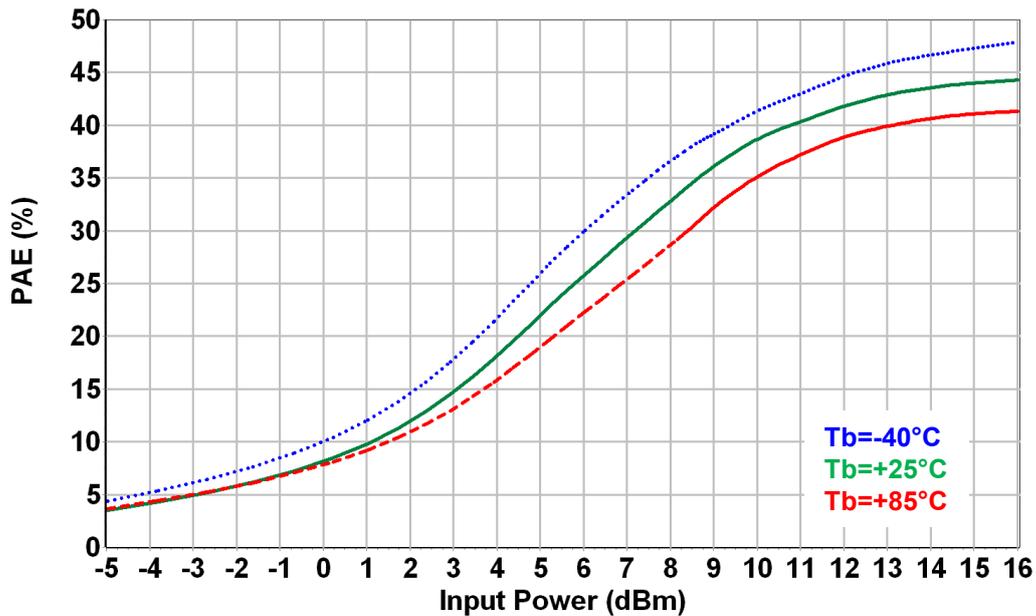
Biassing conditions: $V_d = +7.5V$, $I_{dq} = 120mA$ set at $T_b = +25^\circ C$, kept constant vs temperature.

Test conditions at $T_{backside} = -40^\circ C / +25^\circ C / +85^\circ C$

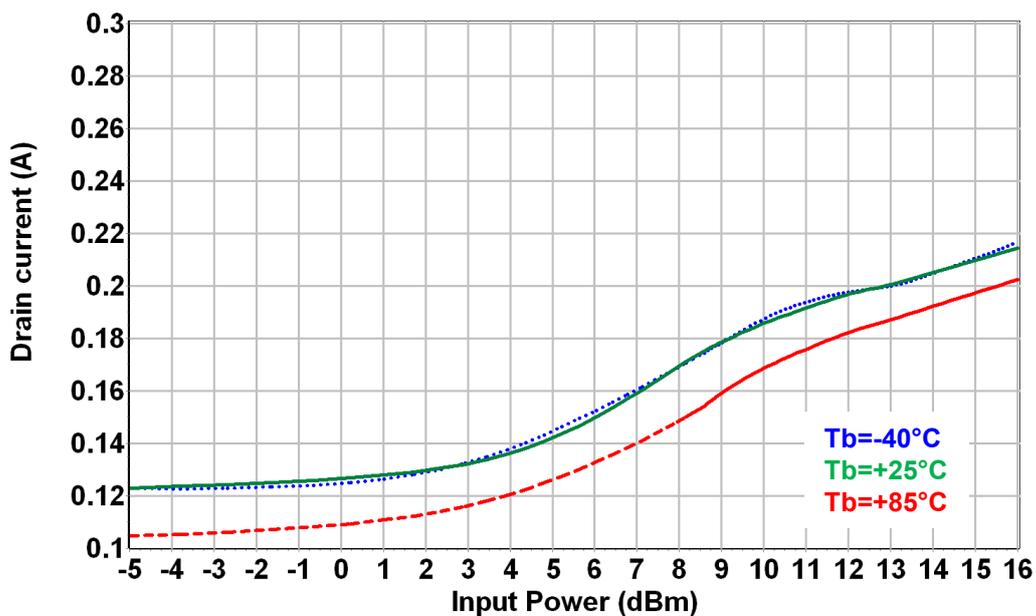
Frequency : 1.3 GHz in CW measurements

Measurements are given in the connectors' access plans, using the board given in the paragraph "Evaluation board".

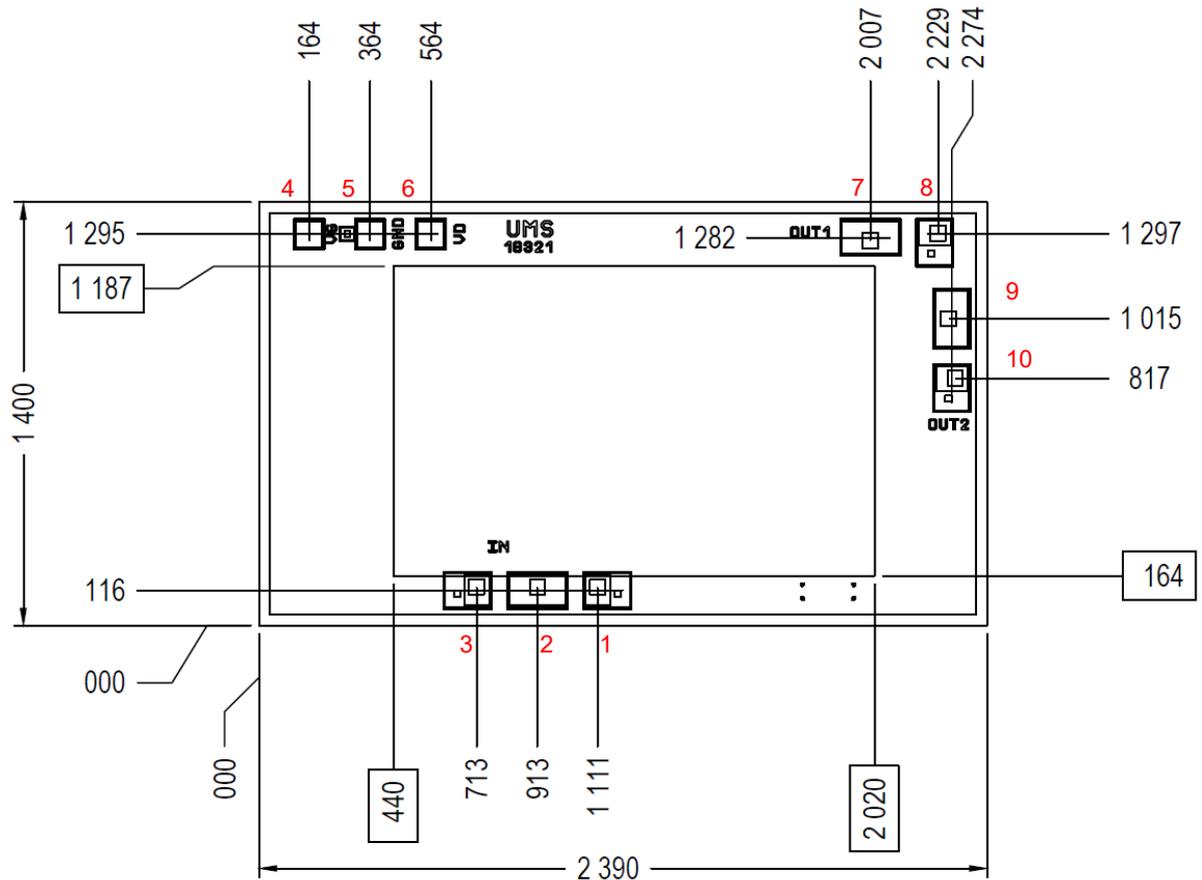
PAE versus input power and Temp



Drain current versus input power and Temp



Mechanical Drawing

UNITS : μm Tol : $\pm 35\mu\text{m}$

XXX: Air Bridge Area

Chip thickness: $70\mu\text{m}$

All dimensions are in micrometers

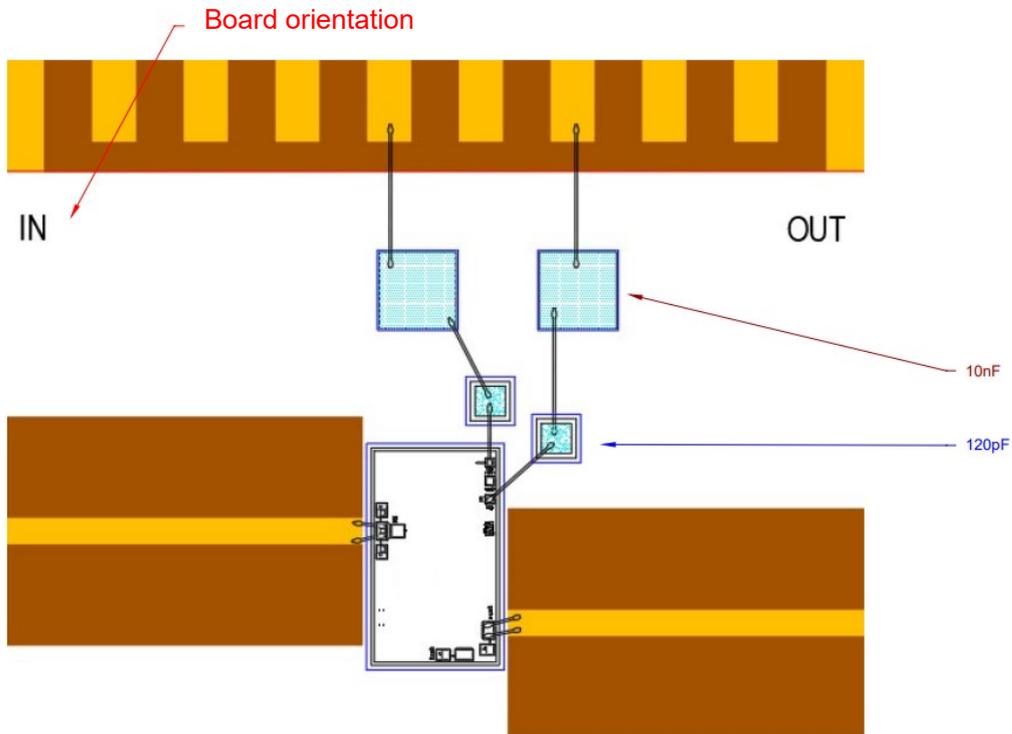
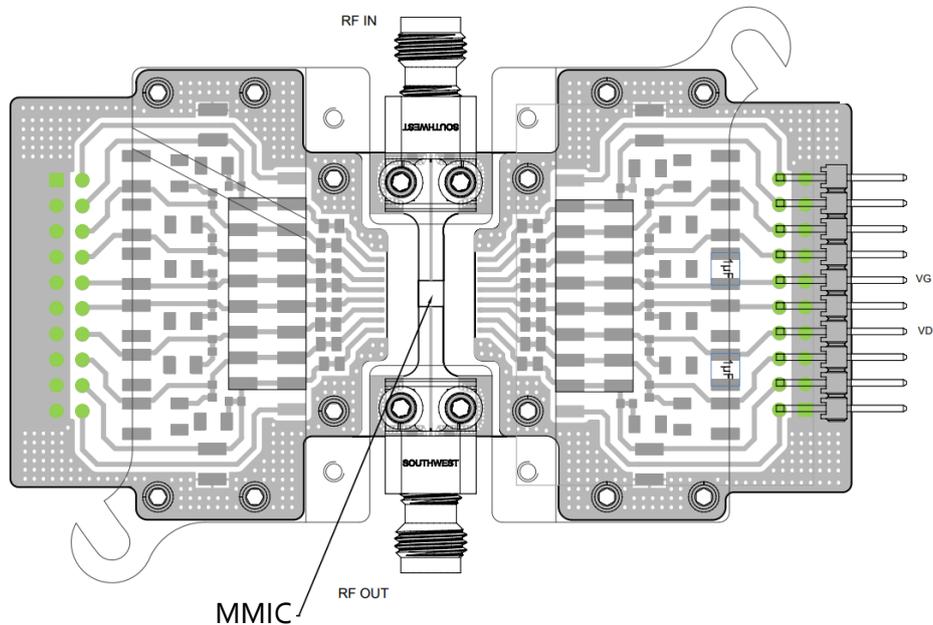
Chip size: $1400\mu\text{m} \times 2390\mu\text{m} \pm 35\mu\text{m}$

PAD Number	Name	Description	Pad size
2	IN	Input RF port (on West Side)	$120\mu\text{m} \times 200\mu\text{m}$
4	VG	DC Gate voltage	$100\mu\text{m} \times 100\mu\text{m}$
6	VD	DC Drain voltage	$100\mu\text{m} \times 100\mu\text{m}$
7	OUT1	Output RF (on East Side)	$120\mu\text{m} \times 200\mu\text{m}$
9	OUT2	Output RF (on South Side)	$120\mu\text{m} \times 200\mu\text{m}$
1,3,8,10	GND	Ground from RF INOUT Cells	$120\mu\text{m} \times 88\mu\text{m}$
5	GND	Ground	$100\mu\text{m} \times 100\mu\text{m}$

Note: only OUT1 or OUT2 must be used.

Evaluation board

- Decoupling capacitors of 100pF ±5% (chip capacitor), 10nF ±10% (chip capacitor) and 1μF ±10% (SMD capacitors) are recommended on Vg and Vd accesses.
- See application note AN0030 for details on the evaluation board and board losses assessment.



ESD sensitivity

Standard	Value
ESD STM5.1-1998 :	HBM Class 1A (between 250V and 500V)

Recommended reflow process assembly

Refer to the application note AN0001 available at <https://www.ums-rf.com> for die attach.

Recommended environmental management

UMS products are compliant with the regulation in particular with the directives RoHS N°2011/65 and REACH N°1907/2006. More environmental data are available in the application note AN0019 also available at <https://www.ums-rf.com>.

Recommended ESD management

Refer to the application note AN0020 available at <https://www.ums-rf.com> for ESD sensitivity and handling recommendations for the UMS products.

Ordering Information

Chip form : CHA5005-99F/XY
Gelpack box: XY = 00

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